

**IN THE CLAIMS:**

Claims 1, 2, 6, and 10-12 are amended. Pending claims stand as follows.

1 (Currently Amended): A method for forming a pattern of a liquid crystal display (LCD) device, comprising:

providing a cliché having at least a first groove structure having a first width and a second groove structure having a second width equal to at least a multiple of the first width and an interval;

filling a resist material into the first and second groove structures of the cliché;  
and

applying the resist material filled into the first and second groove structures of the cliché onto an etching object layer of a substrate of the liquid crystal display device.

2 (Currently Amended): The method of claim 1, further comprising preparing a cliché including providing a cliché substrate, forming a buffer layer on the cliché substrate, and forming the first and second groove structures by patterning the buffer layer.

3 (Original): The method of claim 2, wherein the buffer layer includes a metal layer.

4 (Original): The method of claim 2, wherein the buffer layer includes an organic layer.

5 (Original): The method of claim 1, wherein applying the resist material onto an etching object layer comprises:

contacting and rotating a printing roll onto the cliché to transfer the resist material filled in the first and second groove structures to a surface of the printing roll; and

contacting the resist material formed on the surface of the printing roll to transfer the resist material from the printing roll onto the etching object layer by rotating the printing roll.

6 (Currently Amended): The method of claim 1, wherein applying the resist material onto an etching object layer comprises:

contacting the etching object layer formed on the substrate of the liquid crystal display device ~~where an etching object layer is formed onto~~ with the cliché;

applying heat or pressure to the substrate of the liquid crystal display device; and

detaching the substrate of the liquid crystal display device from the cliché to transfer the resist material filled in the first and second groove structures onto the etching object layer.

7 (Original): The method of claim 1, wherein the etching object layer includes a metal layer.

8 (Original): The method of claim 1, wherein the etching object layer includes one of SiNx and SiOx.

9 (Original): The method of claim 1, wherein the etching object layer includes an organic layer.

10 (Currently Amended): The method of claim 1, wherein filling a resist material into the first and second groove structures of the cliché comprises:  
depositing the resist material along an entire surface of the cliché; and  
contacting a doctor blade onto the surface of the cliché, ~~[[and]]~~ flattening a ~~surface of the cliché to fill~~ the resist material into the first and second groove structures and removing the resist material that remains on the surface of the cliché.

11 (Currently Amended): A method for forming a pattern of an LCD device, comprising:  
forming a buffer layer on a substrate by depositing one of an organic material and a metal material;  
providing a cliché having at least first and second groove structures by patterning the buffer layer, the first groove structure having a first width and ~~[[a]]~~ the second groove structure having a second width including a multiple of the first width and an interval;  
depositing a resist material onto a surface of the cliché;

~~flattening the surface of the cliché using a doctor blade to fill the~~ resist material into the first and second groove structures and removing the resist material from the surface of the cliché;

transferring the resist material filled in the first and second groove structure of the cliché onto a printing roll; and

applying the resist material formed onto the printing roll onto an etching object to form a resist pattern having a uniform thickness.

12 (Currently Amended): A method for forming a pattern of an LCD device, comprising:

forming a buffer layer on a substrate of a cliché by depositing one of an organic material and a metal material on the cliché substrate;

providing on the [[a]] ~~cliché~~ having at least a first groove structure having a first width and a second groove structure having a second width equal to a multiple of the first width and an interval;

depositing a resist material on a surface of the cliché;

~~flattening the surface of the cliché using a doctor blade to fill the~~ resist material into the first and second groove structures and removing the resist material that remains on the surface of the cliché;

forming an etching object layer on a substrate of the LCD device, attaching [[a]] the substrate of the LCD device, including the ~~where an etching object layer is formed~~ onto the cliché and applying at least one of heat and pressure; and

detaching the substrate of the LCD device, including the etching object layer,  
from the cliché to transfer the resist material filled in the first and second groove  
structures of the cliché onto the etching object layer and to form a resist pattern.